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INFORMATION DISCLOSURE
STATEMENT BY APPLICANT

(Use several sheets if necessary)

Ki-Ho Baik et al.
Applicants

April 2, 2004
Filing Date

Unknown
Group

U. S. PATENT DOCUMENTS

Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
<u>BR</u>	4,102,683	07/25/78	DiPiazza	96	38.4	
<u>BR</u>	5,554,485	09/10/96	Dichiara et al.	430	271.1	
<u>BR</u>	5,723,237	03/03/98	Kobayashi et al.	430	30	
<u>BR</u>	5,879,853	03/09/99	Azuma	430	166	
<u>BR</u>	5,879,863	03/09/99	Azuma et al.	430	322	
<u>BR</u>	5,935,768	08/10/99	Biche et al.	430	401	
<u>BR</u>	6,048,672	04/11/00	Cameron et al.	430	327	
<u>BR</u>	6,703,169	03/09/04	Fuller et al.	430	5	

U. S. PATENT APPLICATION DOCUMENTS

Examiner Initial	Document Number	Publication Date	Name	Class	Subclass	Filing Date
<u>BR</u>	2002/0012876 A1	01/31/02	Angelopolous et al.	430	271.1	08/17/01
<u>BR</u>	2002/0182514 A1	12/05/02	Montgomery et al.	430	5	05/03/01

Brittany Raymond

Examiner

Date Considered

1/18/2007

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FOREIGN PATENT DOCUMENTS

<u>Examiner Initial</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Name</u>	<u>Class</u>	<u>Subclass</u>	<u>Translation (If Appropriate)</u>
<u>BR</u>	EP 0987600	03/22/00	Adams et al.	G03F	7/09	
<u>BR</u>	EP 0989460	03/29/00	Shimomura et al.	G03F	7/004	
<u>BR</u>	JP 10048831	02/20/98	Sony Corp.	G03F	007/11	Abstract

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

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- BR P. Buck et al., "Performance of the ALTA® 3500 scanned-laser mask lithography system", *Proceedings of the SPIE Conference on Photomask and X-Ray Mask Technology V*, Kawasaki, Japan, SPIE Vol. 3412, pp. 67-78 (April 1998).
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- BR M. Zuniga et al., "Application of a General Reaction/Diffusion Resist Model to Emerging Materials with Extension to Non-Actinic Exposure", *SPIE*, Vol. 3049, pp. 256-268 (1997).

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